

PI6C102

Precision Clock Synthesizer for Mobile PCs

Features

- Two copies of CPU clock with V_{DD} of $2.5V \pm 5\%$
- 100 MHz or 66.6 MHz operation
- Six copies of PCI clock, (synchronous with CPU clock) 3.3V
- One copy of Ref. Clock @ 14.31818 MHz (3.3 V_{TTL})
- Low cost 14.31818 MHz crystal oscillator input
- Power management control
- Isolated core V_{DD}, V_{SS} pins for noise reduction
- 28-pin SSOP package (H)

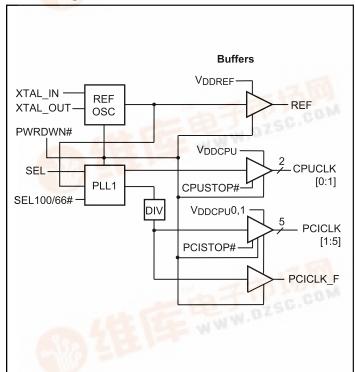
Description

The PI6C102 is a high-speed low-noise clock generator designed to work with the Pericom's PI6C18x clock buffer to meet all clock needs for Mobile Intel Architecture platforms. CPU and chipset clock frequencies of 66.6 MHz and 100 MHz are supported.

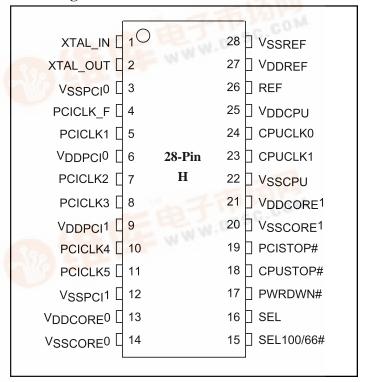
Split supplies of 3.3V and 2.5V are used. The 3.3V power supply powers a portion of the I/O and the core. The 2.5V is used to power the remaining outputs. 2.5V signaling follows JEDEC standard 8-X. Power sequencing of the 3.3V and 2.5V supplies is not required.

An asynchronous PWRDWN# signal may be used to orderly power down (or up) the system.

Block Diagram



Pin Configuration







Pin Description

I III Descri	ption			
Pin	Signal Name	Type	Qty.	Description
1	XTAL_IN	I	1	14.318 MHz crystal input
2	XTAL_OUT	О	1	14.318 MHz crystal output
3,12	V _{SSPCI} [0:1]	ground	2	Ground for PCI clock outputs
4	PCICLK_F	О	1	Free running PCI clock output
5,7,8,10,11	PCICLK[1:5]	О	5	PCI clock outputs, TTL comatible 3.3V
6,9	V _{DDPCI} [0:1]	power	2	Power for PCI clock outputs
21	V _{DDCORE 1}	power	1	Isolated power for core
20	V _{SSCORE 1}	ground	1	Isolated ground for core
15	SEL100/66#	I	1	Select pin for enabling 100 MHz or 66 MHz H = 100 MHz. L = 66 MHz
16	SEL	I	1	Test or Active Mode Select
17	PWRDWN#	I	1	Powers down device when held LOW
18	CPUSTOP#	I	1	Stops CPU clocks LOW if held LOW
19	PCISTOP#	I	1	Stops PCI clocks LOW if held LOW
22	V _{SSCPU}	ground	1	Ground for CPU outputs
23,24	CPUCLK[0:1]	О	2	CPU and Host clock outputs 2.5V
25	V _{DDCPU}	power	1	Power for CPU outputs
26	REF	О	1	14.318 MHz clock output
27	V _{DDREF}	power	1	Power for REF outputs
28	V _{SSREF}	ground	1	Ground for REF outputs

Select Functions

SEL100/66#	SEL	Function
0	0	Hi-Z
0	1	66 MHz active
1	0	Test Mode
1	1	100 MHz active

Function	Outputs				
Description	CPU [0:1]	PCI[0:5], PCIF	REF		
Hi-Z	Hi-Z	Hi-Z	Hi-Z		
Test Mode	TCLK/2	TCLK/6	TCLK		

${\bf Clock\,Enable\,Configuration}$

TCLK is a test clock over driven on he XTAL_IN inpu during test mode.

CPU_STOP#	PCI_STOP#	PWR_DWN#	CPUCLK [0:1]	PCICLK[1:5]	PCICLK_F	Other Clocks	Crystal	VCO's
X	X	0	low	low	low	stopped	off	off
0	0	1	low	low	33 MHz	running	running	running
0	1	1	low	33 MHz	33 MHz	running	running	running
1	0	1	100/66 MHz	low	33 MHz	running	running	running
1	1	1	100/66 MHz	33 MHz	33 MHz	running	running	running

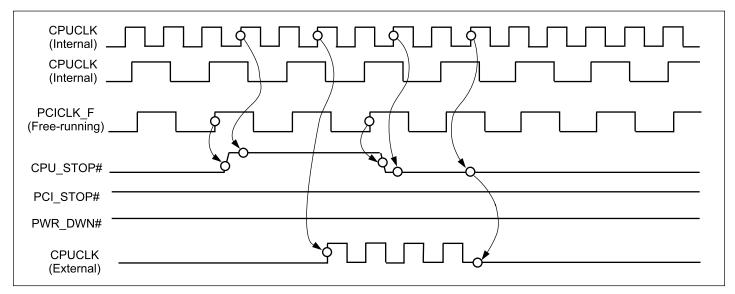


Power Management Timing

Cignal	Signal State	Latency
Signal	Signal State	No. of rising edges of free running PCICLE 1 1 1 1
CPU_STOP#	0 (disabled)	1
	1 (enabled)	1
PCI_STOP#	0 (disabled)	1
	1 (enabled)	1
PWR_DWN#	1 (normal operation)	3ms
	0 (power down)	2 max.

Notes:

- 1. Clock on/off latency is defined as the number of rising edges of free running PCICLKs between when the clock disable goes low/high to when the first valid clock comes out of
- 2. Power-up latency is from when PWR_DWN# goes inactive (HIGH) to when the first valid clocks are driven from the device.



CPU STOP# Timing Diagram

Notes:

- 1. All timing is referenced to the CPUCLK.
- 2. The Internal label means inside the chip and is a reference only.
- 3 CPU STOP# is an input signal that must be made synchronous to the free running PCI F.
- 4. ON/OFF latency shown in the diagram is 2 CPU clocks.
- 5. All other clocks continue to run undisturbed.
- 6. PWR_DWN# and PCI_STOP# are shown in a HIGH state.
- 7. Diagrams shown with respect to 66 MHz. Similar operation as CPU = 100 MHz.

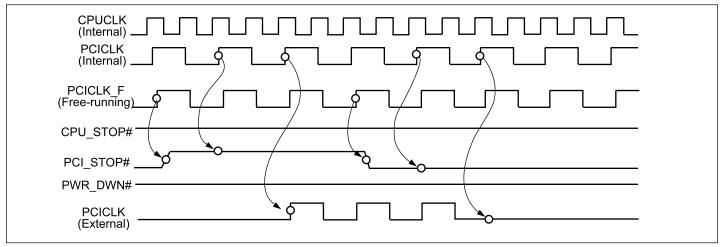
CPU STOP# is an input signal used to turn off the CPU clocks for low power operation. CPU_STOP# is asserted asynchronously by the external clock control logic with the rising edge of free running PCI clock and is internally synchronized to the external PCICLK F output. All other clocks continue to run while the CPU clocks are

disabled. The CPU clocks are always stopped in a LOW state and started guaranteeing that the high pulse width is a full pulse. CPU clock on latency is 2 or 3 CPU clocks and CPU clock off latency is 2 or 3 CPU clocks.



PCI_STOP# is an input signal used to turn off PCI clocks for low power operation. PCI clocks are stopped in the LOW state and

started with a guaranteed full high pulse width. There is ONLY one rising edge of external PCICLK after the clock control logic.



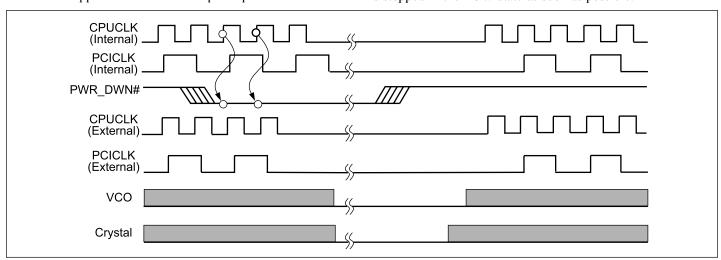
PCI STOP# Timing Diagram

Notes:

- 1. All timing is referenced to the CPUCLK.
- 2. PCI STOP# signal is an input signal which must be made synchronous to PCI F output.
- 3 Internal means inside the chip.
- 4. All other clocks continue to run undisturbed.
- 5. PWR_DWN# and CPU_STOP# are shown in a high state.
- 6. Diagrams shown with respect to $66 \, \text{MHz}$. Similar operation as CPU = $100 \, \text{MHz}$.

The PWR_DWN# is used to place the device in a very low power state. PWR_DWN# is an asynchronous active low input. Internal clocks are stopped after the device is put in power-down mode.

The power-on latency is less than 3ms. PCI_STOP# and CPU_STOP# are "don't cares" during the power-down operations. The REF clock is stopped in the LOW state as soon as possible.



PWR DWN# Timing Diagram

Notes:

- 1. All timing is referenced to the CPUCLK.
- 2. The Internal label means inside the chip and is a reference only.
- 3. PWR DWN# is an asynchronous input and metastable conditions could exist. The signal is synchronized inside the part.
- The shaded sections on the VCO and the Crystal signals indicate an active clock.
- 5. Diagrams shown wth respect to 66 MHz. Similar operation as CPU = 100 MHz.



Maximum Ratings

(Above which the useful life may be impaired. For user guidelines, not tested.)

Storage Temperature65°C to +150°C
Ambient Temperature with Power Applied0°C to +70°C
3.3V Supply Voltage to Ground Potential
2.5V Supply Voltage to Ground Potential
DC Input Voltage0.5V to+4.6V

Note:

Stresses greater than those listed under MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

DC Electrical Characteristics (V_{DDQ3}=+3.3V±5%, V_{DDQ2}=+2.5V±5%, T_A=0°C to +70°C)

PI6C102 Condition	$\begin{aligned} \text{Max. 2.5V Supply Consumption} \\ \text{Max. discrete cap loads,} \\ V_{DDQ2} &= 2.625V \\ \text{All static inputs} &= V_{DDQ3} \text{ or } V_{SS} \end{aligned}$	$\begin{aligned} \text{Max. 3.3V Supply Consumption} \\ \text{Max. discrete cap loads,} \\ \text{$V_{DDQ3} = 3.465V$} \\ \text{All static inputs} = V_{DDQ3} \text{ or } V_{SS} \end{aligned}$
Powerdown Mode (PWRDWN# =0)	100μΑ	500μΑ
Active 66 MHz SEL 100/66# = 0	72mA	170mA
Active 100 MHz SEL 100/66# = 1	100mA	170mA



DC Operating Specifications

Symbol	Parameters	Conditions	Min.	Max.	Units	
$V_{DD} = 3.3V \pm$: 5%					
V _{IH3}	Input high voltage	$V_{ m DD}$	2.0	V _{DD} +0.3	X 7	
V _{IL3}	Input low voltage		V _{SS} -0.3	0.8	V	
${ m I}_{ m IL}$	Input leakage current	$0 < V_{IN} < V_{DD}$	-5	+5	μΑ	
$V_{DD} = 2.5V \pm$: 5%					
V _{OH2}	Output high voltage	$I_{OH} = -1 \text{mA}$	2.0		V	
V _{OL2}	Output low voltage	$I_{OL} = 1 \text{mA}$		0.4	V	
$V_{DD} = 3.3V =$	± 5%					
V _{OH3}	Output high voltage	$I_{OH} = -1 \text{mA}$	2.4		3 .7	
V _{OL3}	Output low voltage	$I_{OL} = 1 \text{mA}$		0.4	V	
$V_{DD} = 3.3V \pm$	5%					
V _{POH}	PCI Bus output high voltage	$I_{OH} = -1 \text{mA}$	2.4		3 7	
V _{POL}	PCI Bus output low voltage	$I_{OL} = 1 \text{mA}$		0.55	V	
C _{IN}	Input pin capacitance			5		
C_{XTAL}	Xtal pins capacitance	13.5	18.0	22.5	pF	
C _{OUT}	Output pin capacitance			6		
L _{PIN}	Pin Inductance			7	nН	
$T_{\mathbf{A}}$	Ambient Temperature	No airflow	0	70	°C	



Buffer Specifications

Buffer Name	V _{DD} Range(V)	Impedance (Ω)	Buffer Type
CPU	2.375 -2.625	13.5 - 45	Type 1
REF	3.135 - 3.465	20 - 60	Type 3
PCI	3.135 - 3.465	12 - 55	Type 5

Type 1: CPU Clock Buffers (2.5V)

Symbol	Parameters	Conditions	Min.	Тур.	Max.	Units
I _{OHMIN}	Pull-up current	$V_{OUT} = 1.0V$	-27			
I _{OHMAX}	Pull-up current	$V_{OUT} = 2.375V$			-27	A
I _{OLMIN}	Pull-down current	$V_{OUT} = 1.2V$	27			mA
I _{OLMAX}	Pull-down current	$V_{OUT} = 0.3V$			30	
t _{RH}	2.5V Type 1 output rise edge rate	2.5V ± 5% @ 0.4V-2.0V	1		4	V/ma
t _{FH}	2.5V Type 1 output fall edge rate	2.5V ± 5% @ 2.0V-0.4V	1		4	V/ns

Type 3: REF (3.3V)

Symbol	Parameters	Conditions	Min.	Тур.	Max.	Units
I _{OHMIN}	Pull-up current	$V_{OUT} = 1.0V$	-29			
I _{OHMAX}	Pull-up current	$V_{OUT} = 2.375V$			-23	A
I _{OLMIN}	Pull-down current	$V_{OUT} = 1.2V$	29			mA
I _{OLMAX}	Pull-down current	$V_{OUT} = 0.3V$			27	
t _{RH}	3.3V Type 3 output rise edge rate	$3.3V \pm 5\%$ @ 0.4V-2.4V	0.5		2	V/ma
t _{FH}	3.3V Type 3 output fall edge rate	3.3V ± 5% @ 2.4V-0.4V	0.5		2	V/ns

Type 5: PCI Clock Buffers (3.3V)

Symbol	Parameters	Conditions	Min.	Тур.	Max.	Units
IOHMIN	Pull-up current	$V_{OUT} = 1.0V$	-33			
I _{OHMAX}	Pull-up current	$V_{OUT} = 3.135V$			-33	A
I _{OLMIN}	Pull-down current	$V_{OUT} = 1.95V$	30			mA
I _{OLMAX}	Pull-down current	$V_{OUT} = 0.4V$			38	
t _{RH}	3.3V Type 5 output rise edge rate	3.3V ± 5% @ 0.4V-2.4V	1		4	V//ma
t _{FH}	3.3V Type 5 output fall edge rate	3.3V ± 5% @ 2.4V-0.4V	1		4	V/ns



AC Timing

Figure 1. Host Clock	D	66 MHz		100 MHz			
to PCI CLK Offset	Parameters	Min.	Max.	Min.	Max.	- Units	
t _{HKP} (2.5V)	Host CLK period 15.0 15.5 10.0		10.0	10.5			
t _{HKH} (2.5V)	Host CLK high time	5.2		3.0			
t _{HKL} (2.5V)	Host CLK low time	5.0		2.8	ns		
thrise (2.5V)	Host CLK rise time	0.4	1.6	0.4	1.6	1.6	
t _{HFALL} (2.5V)	Host CLK fall time	0.4	1.6	0.4	1.6		
tJITTER (2.5V)	Host CLK Jitter		250		250	ps	
Duty Cycle (2.5V)	Measured at 1.25V	45	55	45	55	%	
t _{HSKW} (2.5V)	Host Bus CLK Skew		175		175	ps	
t _{PZL} , t _{PZH}	Output enable delay	1.0	8.0	1.0	8.0		
tPLZ, tPHZ	Output disable delay	1.0	8.0	1.0	8.0		
thstb	Host CLK Stabilization from power-up		3		3	ms	
tpKP	PCI CLK period 30.0 ∞ 30.0		30.0	∝	ns		
tpKPS	PCI CLK period stability		500		500	ps	
tPKH	PCI CLK high time	12.0		12.0			
tPKL	PCI CLK low time	12.0		12.0		ns	
tpskw	PCI Bus CLK Skew 500			500	ps		
thpoffset	Host to PCI Clock Offset	1.5	4.0	1.5	4.0	ns	
t _{PSTB}	PCI CLK Stabilization from power-up		3		3	ms	



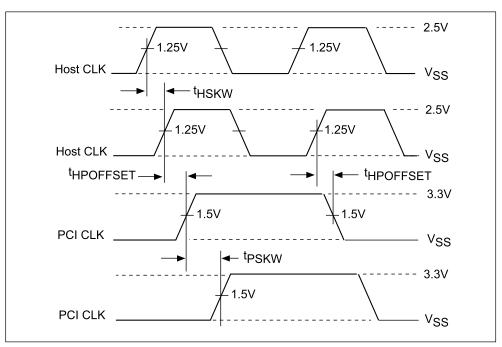


Figure 1. Host Clock and PCI CLK Timing

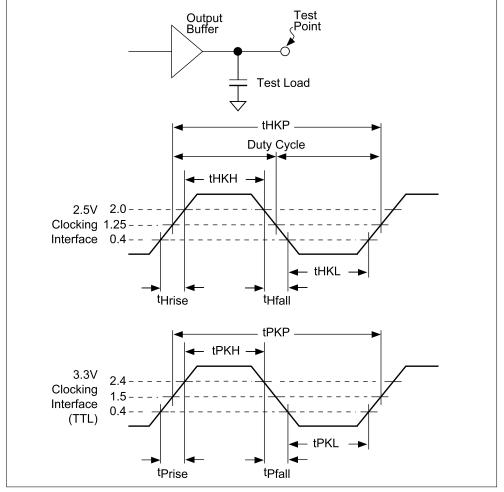
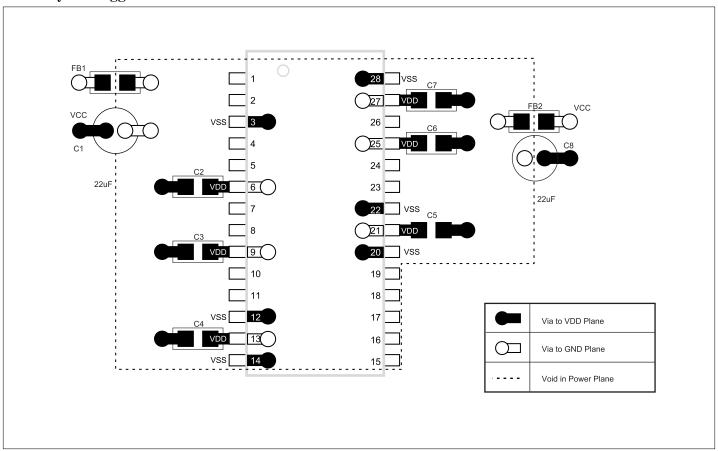


Figure 2. Clock Output Waveforms



PCB Layout Suggestion



Note:

This is only a suggested layout. There may be alternate solutions depending on actual PCB design and layout.

As a general rule, C2-C7 should be placed as close as possible to their respective V_{DD}.

Recommended capacitor values:

C2-C7 0.1µF, ceramic

C1, C8 22µF



Minimum and Maximum Expected Capacitive Loads

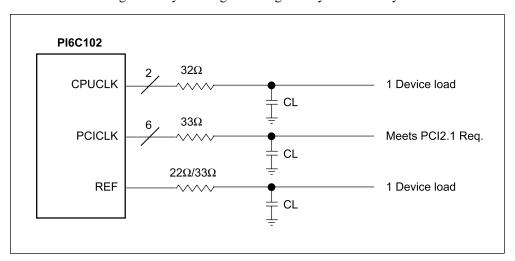
Clock	Min. Load	Max. Load	Units	Notes
CPU Clocks (HCLK)	10	20		1 device load, possible 2 loads
PCI Clocks (PCLK)	30	30	pF	Meets PCI 2.1 requirements
REF	10	20		1 device load

Notes:

- 1. Maximum rise/fall times are guaranteed at maximum specified load for each type of output buffer.
- Minimum rise/fall times are guaranteed at minimum specified load for each type of output buffer.
- Rise/fall times are specified with pure capacitive load as shown. Testing is done with an additional 500Ω resistor in parallel.

Design Guidelines to Reduce EMI

- 1. Place series resistors and CI capacitors as close as possible to the respective clock pins. Typical value for CI is 10pF. Series resistor value can be increased to reduce EMI provided that the rise and fall time are still within the specified values.
- 2. Minimize the number of "vias" of the clock traces.
- 3. Route clock traces over a continuous ground plane or over a continuous power plane. Avoid routing clock traces from plane to plane (refer to rule #2).
- 4. Position clock signals away from signals that go to any cables or any external connectors.



Ordering Information

P/N	Description		
PI6C102H	28-pin SSOP Package		